Tecnite

THERMAL PAD - DT30-H25

Features

- Thermal conductivity: 3.0 W/mK
- High conformability
- Cost effective solution
- Electrically insulating
- Naturally sticky
- Custom die-cut parts: custom configurations available



Applications

- Between electronic components: semiconductors, ICs, CPUs, MOS and heasink
- LEDs, LCD TV, telecom devices, wireless hubs, PCs, power supply etc.
- Cooling and thermal modules
- In all applications where a metal housing is used as heatsink

Reach RoHS Compliant Underwriters Laboratories

Part number code (example):

UDT 10/H10 - T10

- T10 → Thickness: 1.0 mm
- H10 → Hardness: 10 Shore C
- 10 → Thermal Conductivity: 1.0 W/mK
- UDT → UDT: Thermal Pad

TECNITE DT30-H25

Properties	Unit	DT30-H25	Test Method
Composition		Silicone & ceramic filled	
Colour		Blue	
Thickness range	mm	0.5 - 5.0	ASTM D734
Hardness	Shore C	35±5	ASTM D2240
Density	g/cc	3.0	ASTM D792
Temperature range	°C	-40 to 150	
Breakdown voltage	kV/mm	≥5.0	ASTM D149
Volume impedance	ohm*cm	10^{12}	ASTM D257
Weight damnify	%	≤1	25 % @ 125 °C 48H
Thermal conductivity	W/mK	3.0±0.3	ISO 22007-2
Tensile strength	KN/m	0.30	ASTM D5470
Elongation	%	64	ASTM D150
Compliances		UL 94 V-0, RoHS, REACH	
Sheet size		Standard: 200*400 mm	ASTM 1204
Shelf life		12 months	< 40 °C
Custom configurations		Custom die-cut parts available. Available with acrylic PSA tape for improved application on one or both sides: • 3M Double Coated Tape 9448HK (will make the pad 0.15 mm thicker on both sides) • 3M Transfer Tape 3M467 (will make the pad 0.06 mm thicker on both sides)	

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